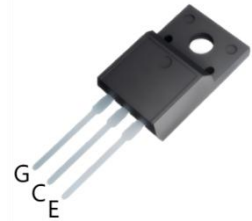
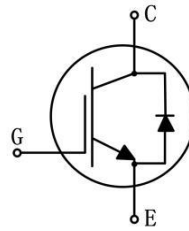


**Trench Field-stop IGBT Discrete**

Parameter	Value	Unit
$V_{CE}$	650	V
$I_C$	30	A
$V_{CE(sat)}$	1.69	V



TO-220F

**Features**

- Positive temperature coefficient.
- Fast Switching
- LOW  $V_{CE(sat)}$
- Reliable and Rugged
- Halogen Free and Green Devices Available

**Applications**

- Motor drives
- Air Condition
- Inverters

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CES}$	650	V
Gate-emitter voltage	$V_{GES}$	$\pm 30$	V
Continuous collector current( $T_C=25^\circ C$ )	$I_C$	60	A
Continuous collector current( $T_C=100^\circ C$ )		30	A
Pulsed collector current, tp limited by $T_{vjmax}$	$I_{CM}$	90	A
Diode continuous forward current( $T_C=25^\circ C$ )	$I_F$	60	A
Diode continuous forward current( $T_C=100^\circ C$ )		30	A
Diode maximum current, tp limited by $T_{vjmax}$	$I_{FM}$	90	A
Operating junction temperature range	$T_{vj}$	-55 to+175	$^\circ C$
Storage temperature range	$T_{Stg}$	-55 to+175	$^\circ C$

**Thermal Characteristics**

Parameter	Symbol	Value		Unit
		Typ	Max.	
Thermal resistance,junction to case for IGBT	$R_{th(j-c)}$	-	0.83	$^\circ C/W$
Thermal resistance,junction to case for Diode	$R_{th(j-c)}$	-	0.65	$^\circ C/W$
Thermal resistance,junction to ambient	$R_{th(j-a)}$	-	40	$^\circ C/W$

**Electrical Characteristics of IGBT ( $T_{vj}=25^{\circ}\text{C}$  unless otherwise noted)**
**Static characteristics**

Parameter	Symbol	Test condition	Value			Unit
			Min.	Typ.	Max.	
Collector-emitter breakdown voltage	$B_{V_{CES}}$	$V_{GE}=0V, I_C=250\mu A$	650	-	-	V
Collector-emitter leakage current	$I_{CES}$	$V_{CE}=650V, V_{GE}=0V$	-	-	10	$\mu A$
Gate leakage current, forward	$I_{GES}$	$V_{GE}=\pm 20V, V_{CE}=0V$	-	-	$\pm 200$	nA
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=1mA$	4.3	5.3	6.3	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=30A$	-	1.69	2	V
		$V_{GE}=15V, I_C=30A, T_{vj}=125^{\circ}\text{C}$	-	1.9	-	V
		$V_{GE}=15V, I_C=30A, T_{vj}=175^{\circ}\text{C}$	-	2.05	-	V

**Dynamic Characteristics**

Parameter	Symbol	Test condition	Value			Unit
			Min.	Typ.	Max.	
Input capacitance	$C_{ies}$	$V_{CE}=25V$	-	1853	-	pF
Output capacitance	$C_{oes}$	$V_{GE}=0V$	-	72	-	pF
Reverse transfer capacitance	$C_{res}$	$f=1MHz$	-	55	-	pF
Total gate charge	$Q_g$	$V_{CC}=520V$	-	98	-	nC
Gate-Emitter Charge	$Q_{ge}$	$V_{GE}=15V$	-	18	-	nC
Gate-Collector Charge	$Q_{gc}$	$I_C=30A$	-	47	-	nC
Short circuit collector current Max.1000 short circuits, times between short circuits: $\geq 1.0s$	$t_{(SC)}$	$V_{GE}=15V$ $V_{CC}\leq 400V$ $T_{J}\leq 175^{\circ}\text{C}$	-	8	-	$\mu s$

**Switching Characteristics**

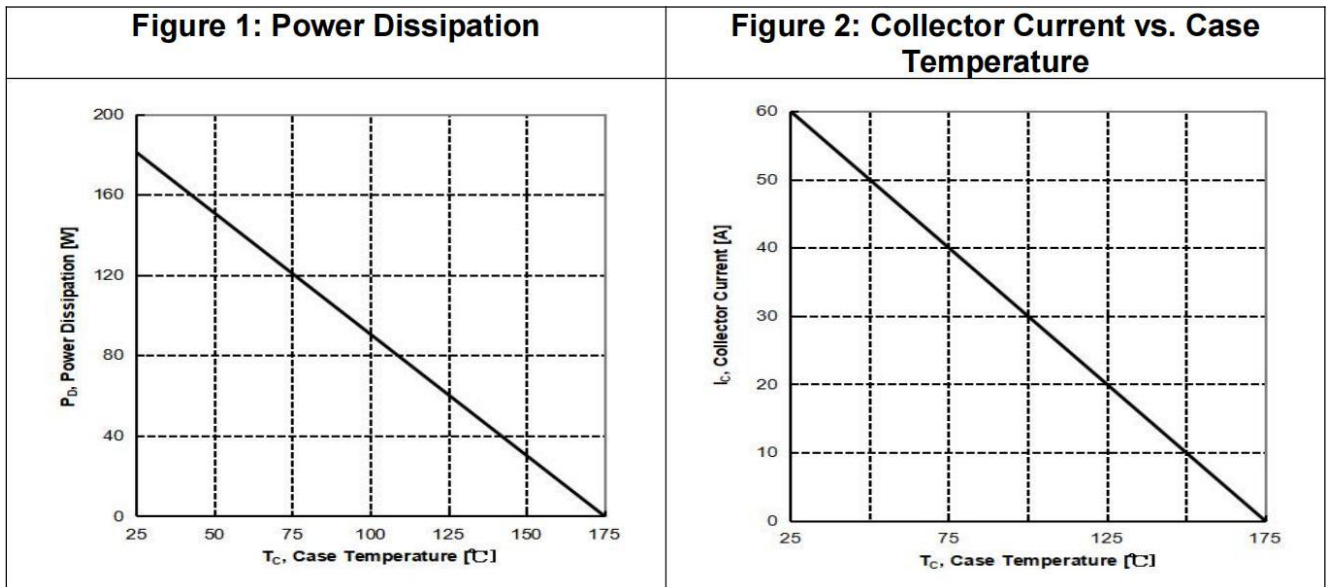
Parameter	Symbol	Test condition	Value			Unit
			Min.	Typ.	Max.	
Turn-on delay time	$t_{d(on)}$	$V_{CC}=400V$ $V_{GE}=15V$ $I_C=30A$ $R_G=5\Omega$ Inductive load	-	16	-	ns
Rise time	$t_r$		-	46	-	ns
Turn-off delay time	$t_{d(off)}$		-	72	-	ns
Fall time	$t_f$		-	80	-	ns
Turn-on energy	$E_{on}$		-	0.52	-	mJ
Turn-off energy	$E_{off}$		-	0.77	-	mJ
Total switching energy	$E_{ts}$		-	1.29	-	mJ
Turn-on delay time	$t_{d(on)}$	$V_{CC}=400V$	-	18	-	ns
Rise time	$t_r$	$V_{GE}=15V$	-	54	-	ns

Turn-off delay time	$t_{d(off)}$	$I_C=30A$ $R_G=5\Omega$ Inductive load $T_{vj}=175^\circ C$	-	90	-	ns
Fall time	$t_f$		-	75	-	ns
Turn-on energy	$E_{on}$		-	0.97	-	mJ
Turn-off energy	$E_{off}$		-	1.36	-	mJ
Total switching energy	$E_{ts}$		-	2.33	-	mJ

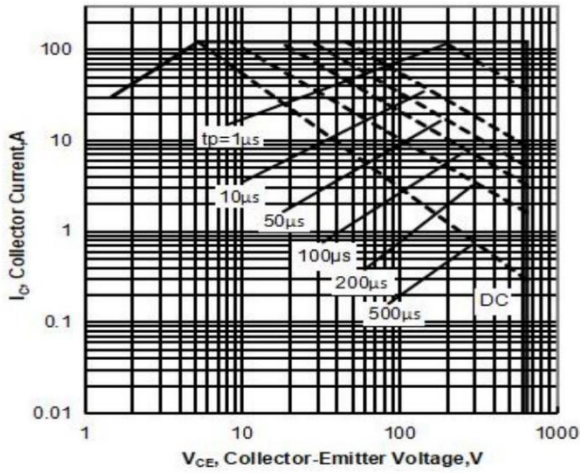
### Diode Characteristics

Parameter	Symbol	Test condition	Value			Unit
			Min.	Typ.	Max.	
Diode forward voltage	$V_F$	$I_F=30A$	-	2	2.3	V
		$I_F=30A$ $T_{vj}=125^\circ C$	-	1.7	-	V
		$I_F=30A$ $T_{vj}=175^\circ C$	-	1.5	-	V
Diode reverse recovery time	$t_{rr}$	$I_F=30A$ $diF/dt=-200A/\mu s$	-	48	-	ns
Diode peak reverse recovery current	$Q_{rr}$		-	80	-	nC
Diode reverse recovery charge	$I_{rrm}$		-	5.1	-	A
Diode reverse recovery time	$t_{rr}$	$I_F=30A$ $diF/dt=-200A/\mu s$ $T_{vj}=175^\circ C$	-	39	-	ns
Diode peak reverse recovery current	$Q_{rr}$		-	127	-	nC
Diode reverse recovery charge	$I_{rrm}$		-	8.5	-	A

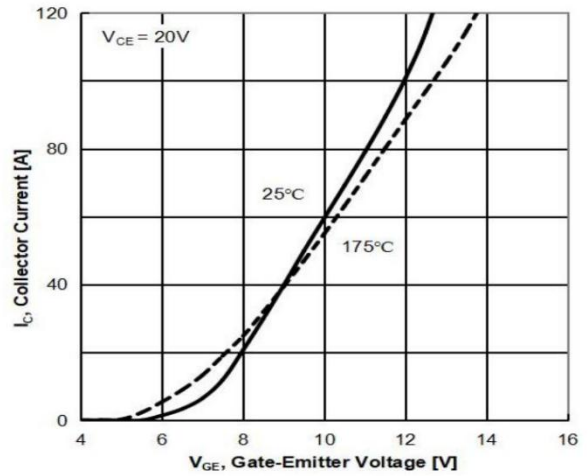
### Typical Characteristics



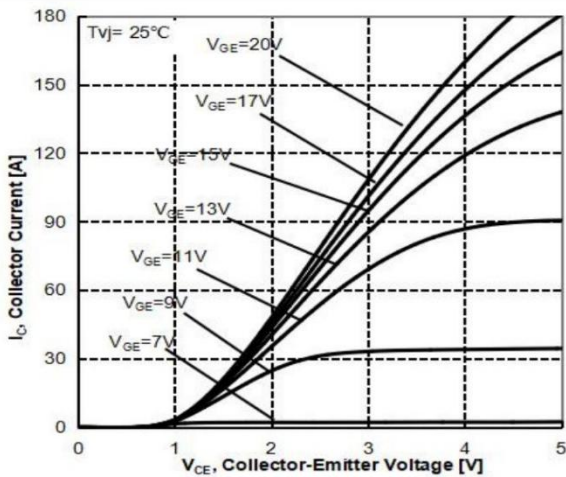
**Figure 3: Safe Operation Area**



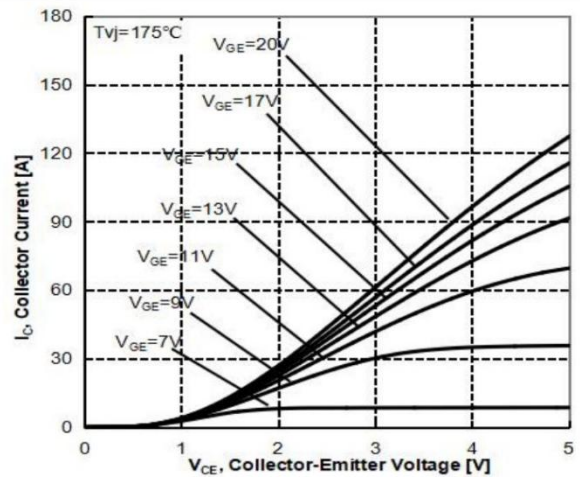
**Figure 4: Typical Transfer Characteristics**



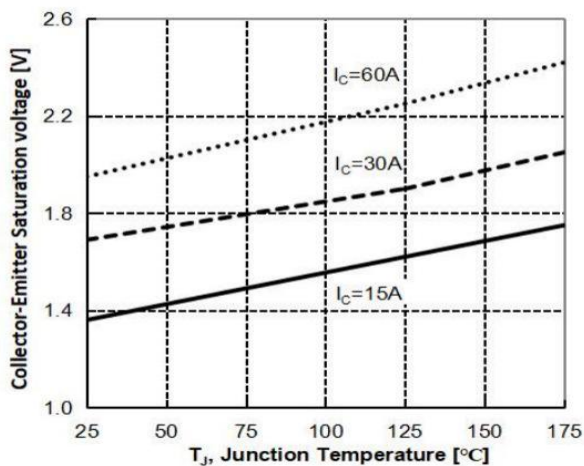
**Figure 5: Typical Output Characteristics**



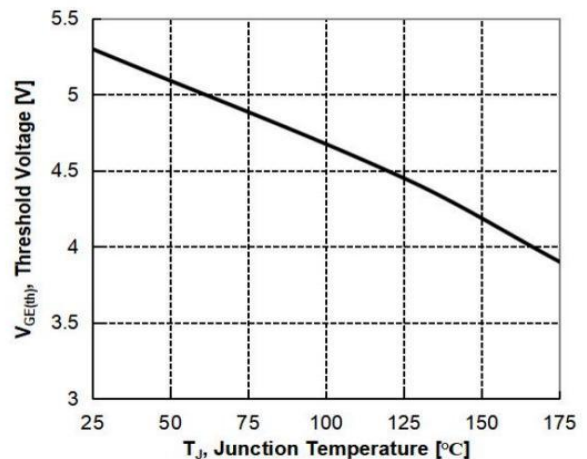
**Figure 6: Typical Output Characteristics**



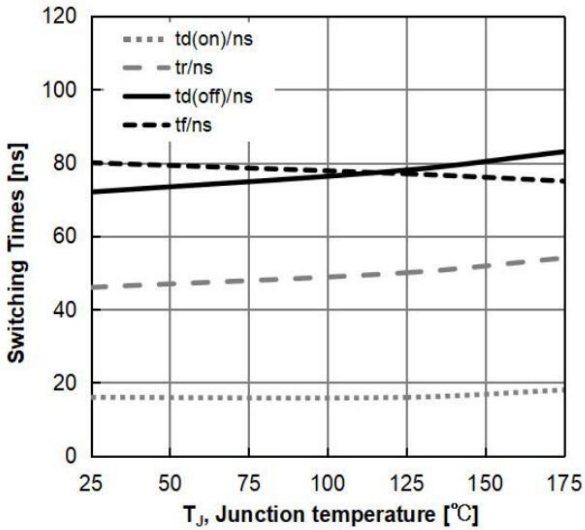
**Figure 7: Typical Collector-Emitter Saturation Voltage vs. Junction Temperature**



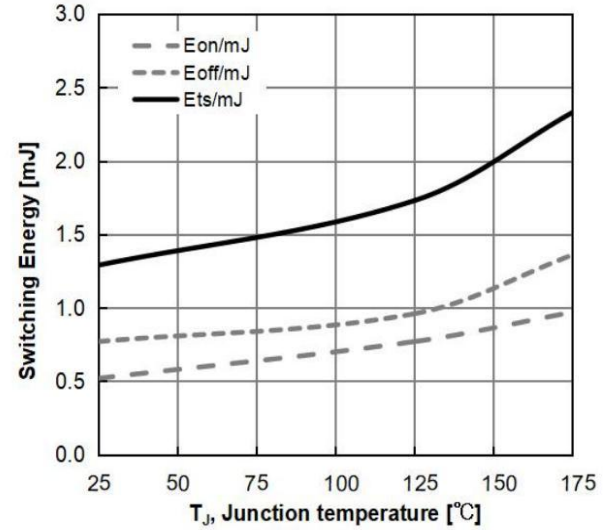
**Figure 8: Typical Gate-Emitter Threshold Voltage vs. Junction Temperature**



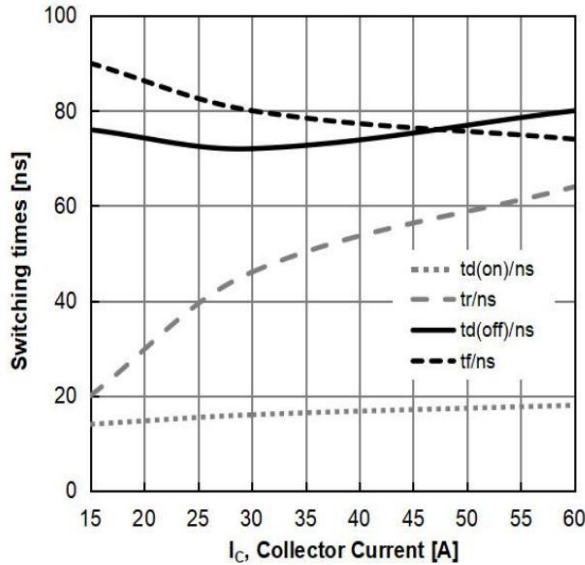
**Figure 11: Typical Switching Times vs. Junction Temperature ( $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $I_C=30A$ )**



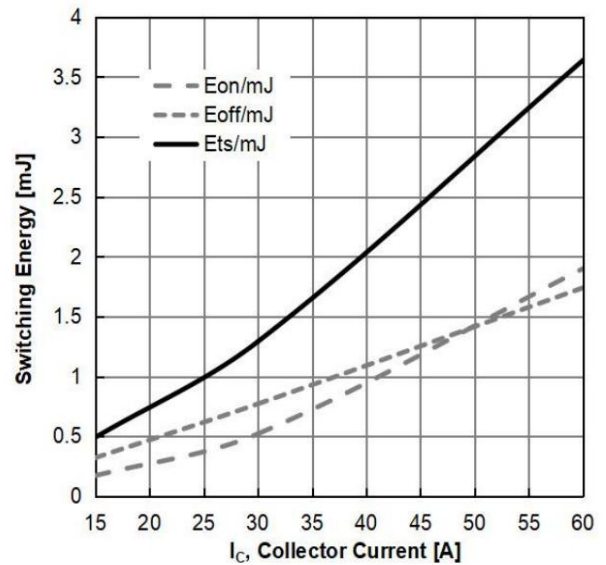
**Figure 12: Typical Switching Energy vs. Junction Temperature ( $V_{CE}=400V$ ,  $V_{GE}=15/0V$ ,  $I_C=30A$ )**



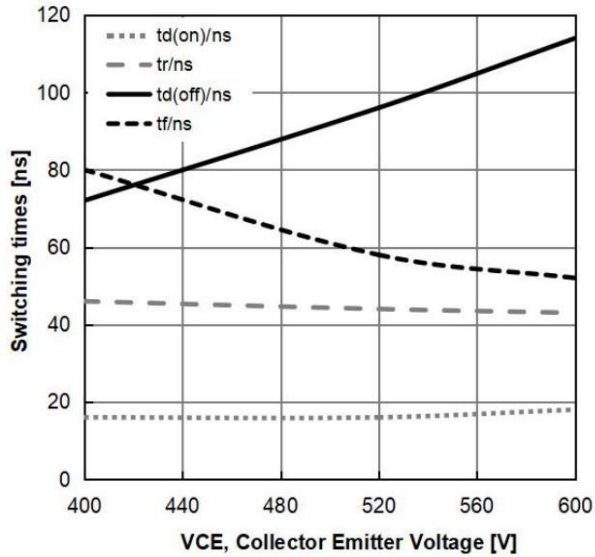
**Figure 13: Typical Switching Times vs. Collector Current ( $T_J=25°C$ ,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ )**



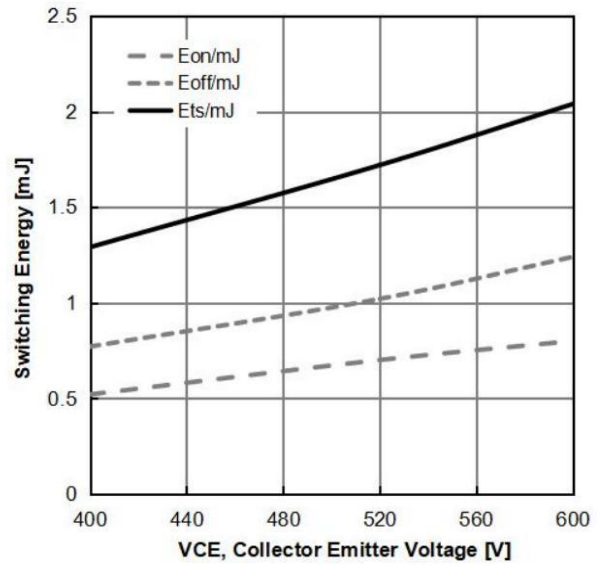
**Figure 14: Typical Switching Energy vs. Collector Current ( $T_J=25°C$ ,  $V_{CE}=400V$ ,  $V_{GE}=15/0V$ )**



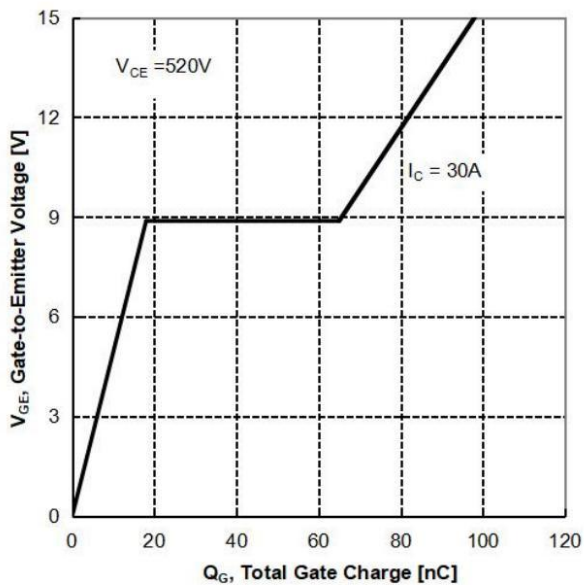
**Figure 15: Typical Switching Times vs. VCE (  $T_J=25^\circ\text{C}, V_{GE}=15/0\text{V}, I_C=30\text{A}$  )**



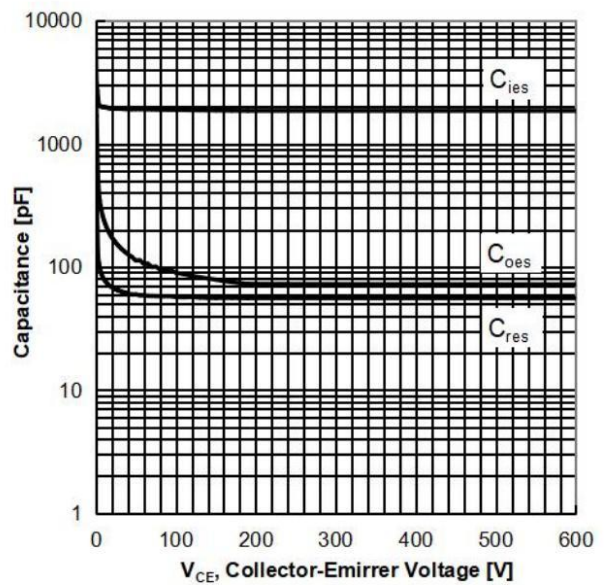
**Figure 16: Typical Switching Energy vs. VCE (  $T_J=25^\circ\text{C}, V_{GE}=15/0\text{V}, I_C=30\text{A}$  )**



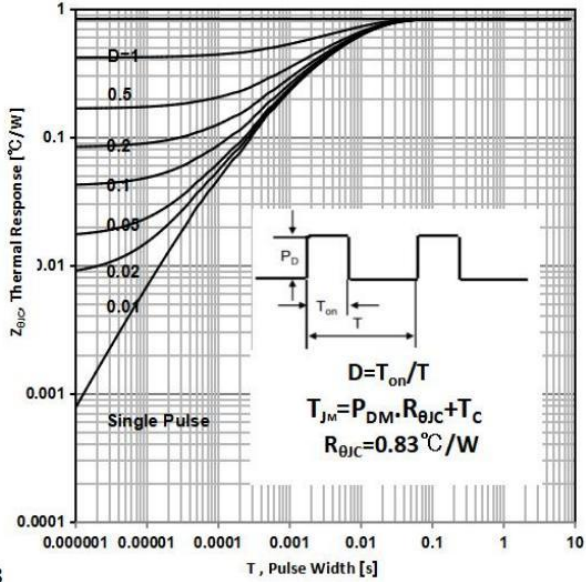
**Figure 17: Typical Gate Charge**



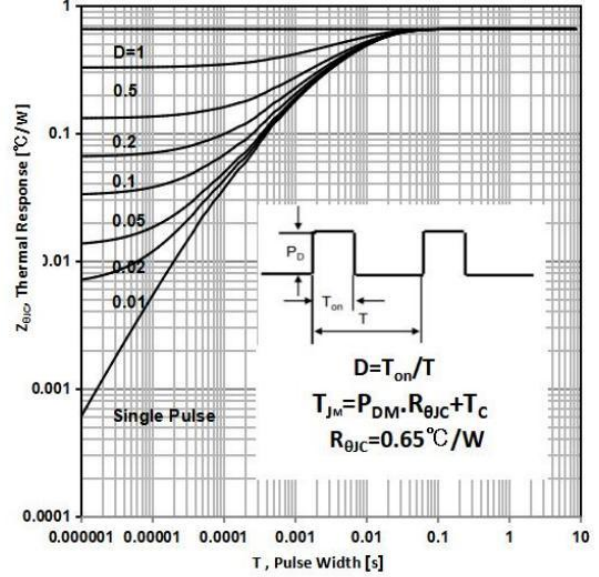
**Figure 18: Typical Capacitance vs. Collector- Emitter Voltage**



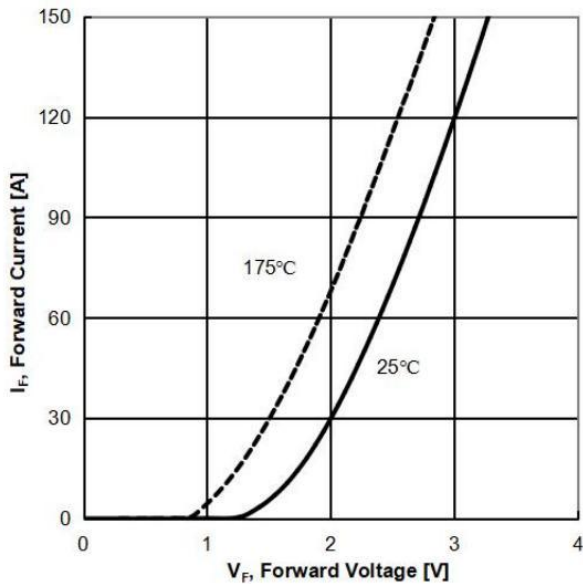
**Figure 19: IGBT Transient Thermal Impedance vs. Pulse Width**



**Figure 20: Diode Transient Thermal Impedance vs. Pulse Width**

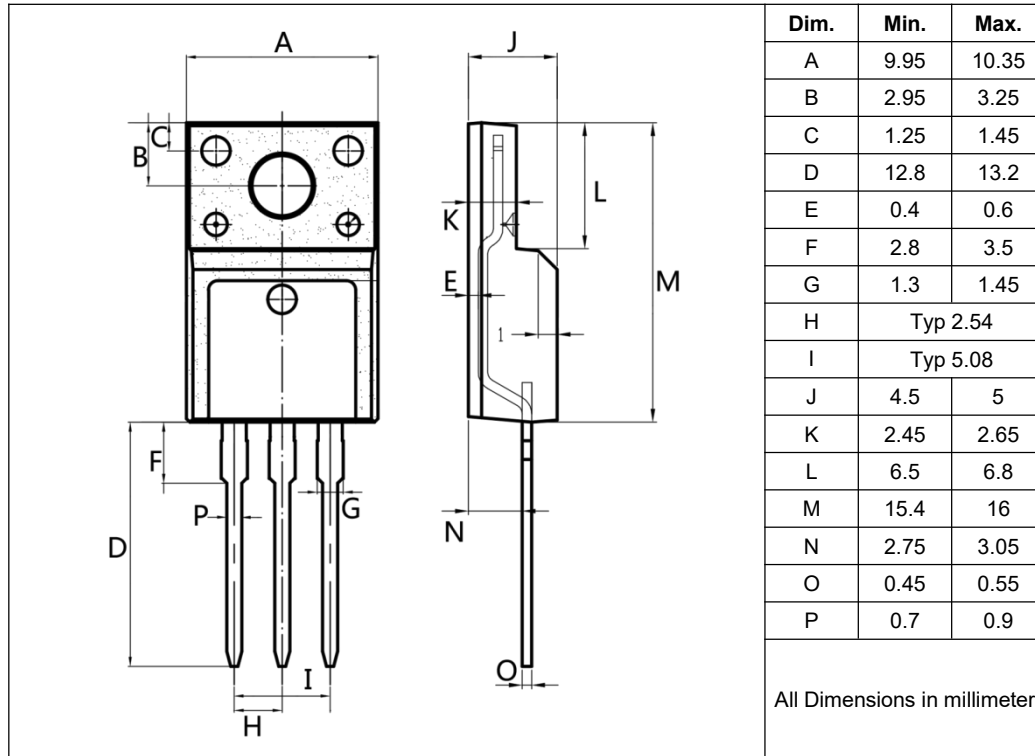


**Figure 21: Typical Diode Forward Current vs. Forward Voltage**



**Package Outlines (Unit: mm)**

**TO-220F**



**\*Important Usage Information and Disclaimer**

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